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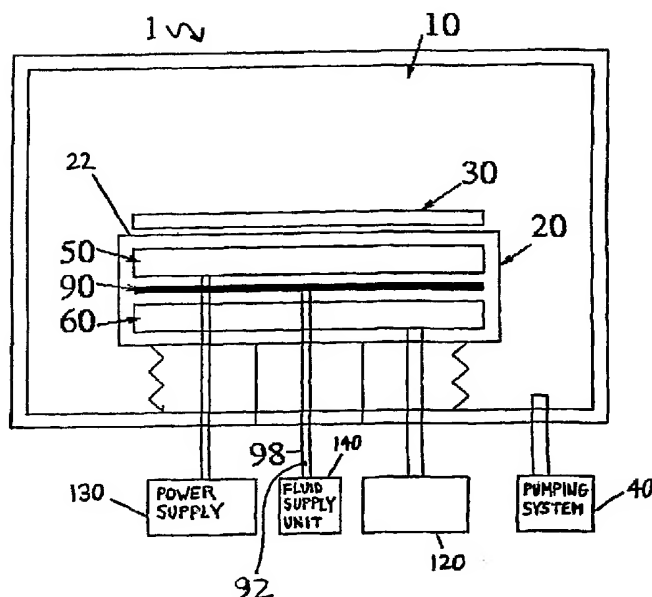
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(54) Title: SUBSTRATE HOLDER HAVING A FLUID GAP AND METHOD OF FABRICATING THE SUBSTRATE HOLDER



(57) Abstract: A substrate holder for supporting a substrate. A heating component is positioned adjacent to a supporting surface and between the supporting surface and a cooling component. A fluid gap is positioned between the cooling component and the heating component, the fluid gap configured to receive a fluid to increase thermal conduction between the cooling component and the heating component. A brazing material is disposed between the cooling component and the heating component, the brazing material disposed adjacent to the fluid gap.

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